

FIT DLP Projector DMD socket

SPECIFICATIONS

Mechanical

Socket compression Force: 4KG min
 Durability: 15 Cycles min

Electrical

Contact Resistance: 35mΩ max.
 Dielectric Withstanding Voltage: 500V
 Insulation Resistance: 800MΩ min.

Physical

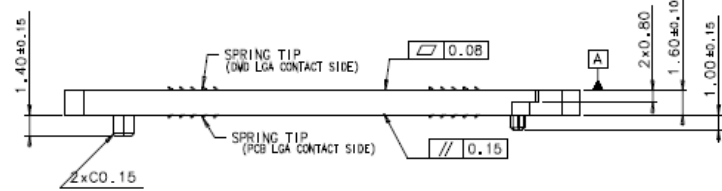
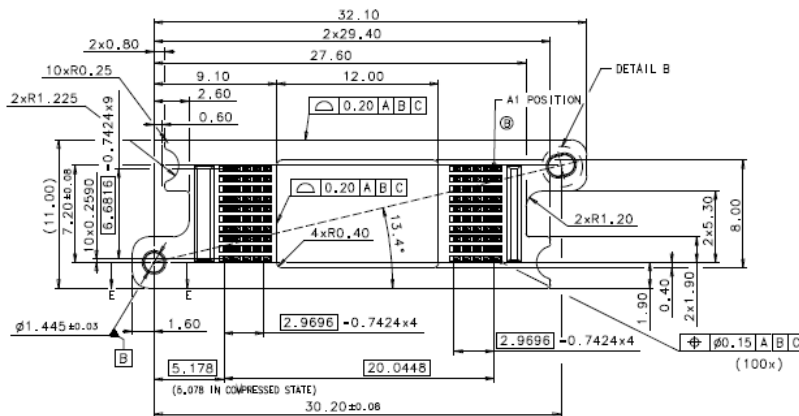
Housing: PEI, UL94V-0, BLACK COLOR
 Contact: BeCu Alloy 390E
 Plating: See "ORDERING INFORMATION"
 Operating Temperature: 0°C to +105°C

LGA 100 SOCKET

TI DLP Series S312 (Pico 1080P) (0.47")
 0.7424mm, 10x10 Array,
 LGA/LGA connector



DRAWING

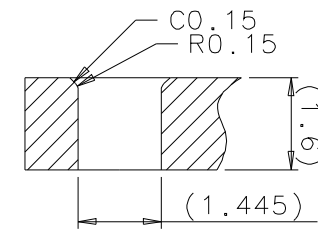
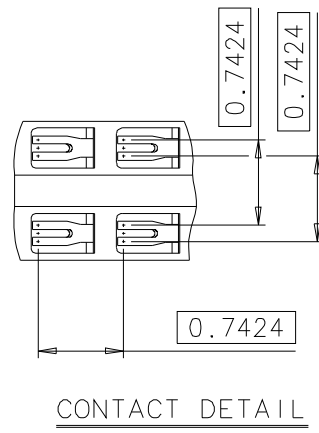
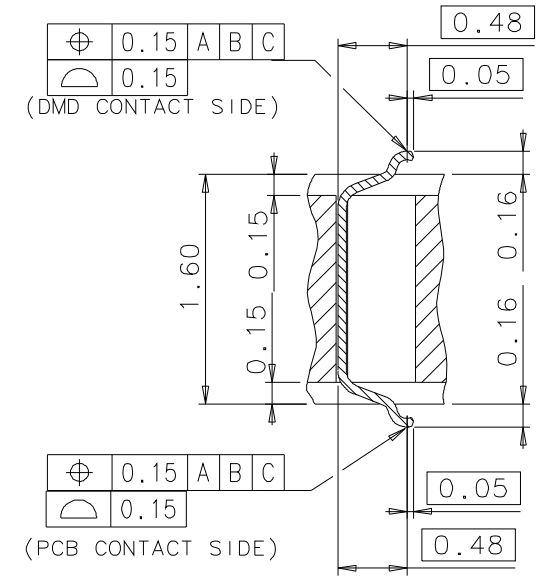
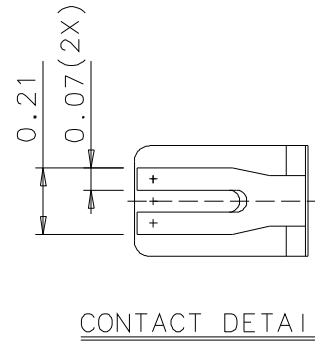
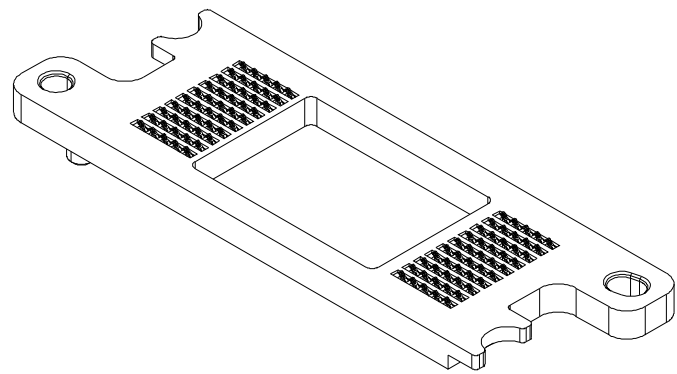


Ordering Information

FIT PN : PE010021-114A-10H

IDEAS GENERATED DRAWING, DON'T CHANGE BY HAND.

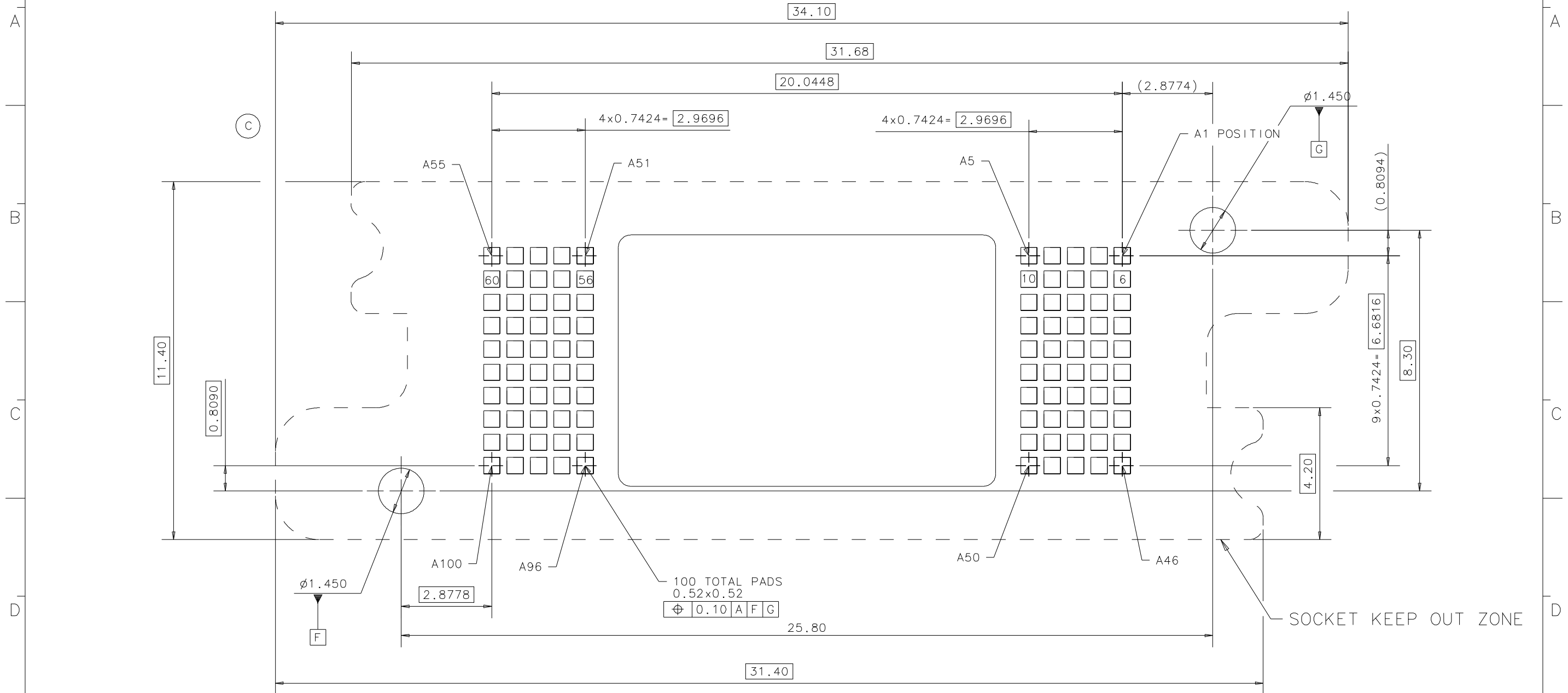
REV.	ECN. NO.	APPD.



X.±	X.° ± 1°	UNITS mm	NAME (INTENDED USE)	FOXCONN® FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X± 0.10	.X° ±	MAT'L	TI 0.7424mm 10x10 ARRAY uLGA CONNECTOR	
.XX± 0.05	.XX° ±	FINISH	PART NO. (INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX±	.XXX° ±		PE010021-114A-10H	TITLE: CUSTOMER DRAWING FOR TI DMD LGA100 CONNECTOR
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			APPD: Simon Szu	DWG NO.: 351-0000-1305
			CHKD: Bono Liao	SCALE SHEET REV.
			DR: Daniel Su 11/2'15	N/A 2/3 C

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REV.	ECN. NO.	APPD.



RECOMMENDED PCB LAYOUT & KEEP OUT ZONE

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.X± 0.10	.X° ±	MAT'L	TI 0.7424mm 10x10 ARRAY uLGA CONNECTOR	
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